

REGISTER BY MAY 18 FOR BEST RATES: www.tms.org/3DMS2020

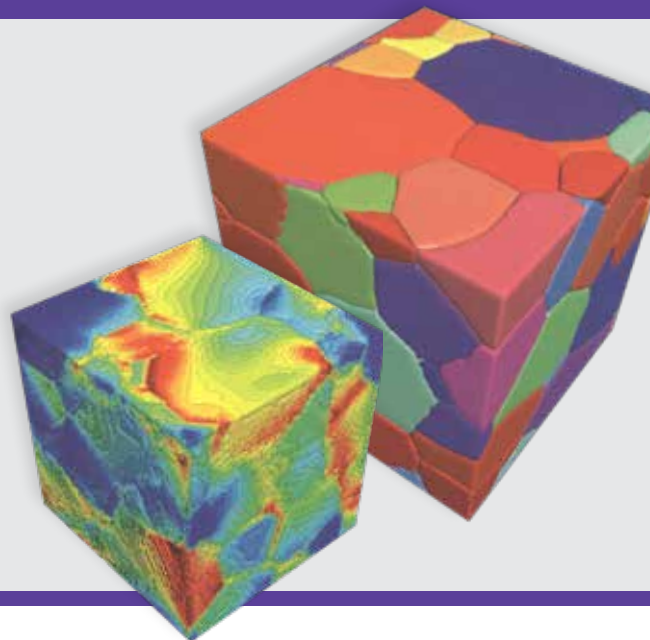
The 5th International Congress on

3DMS

3D Materials Science 2020

June 28-July 1, 2020

Hyatt Regency Washington on Capitol Hill
Washington, D.C., USA



Ensure your place at the premier forum for 3D Materials Science by registering today for the 5th International Congress on 3D Materials Science (3DMS 2020).

The congress program includes, but is not limited to, the following technical topics:

- Methods for materials simulation, modeling, and characterization in 3D
- 3D data processing and reconstruction algorithms
- Process-microstructure-property relationships in 3D
- Materials dynamics in 3D
- Machine learning
- New characterization methods

3DMS 2020 distills the most current knowledge of the field in a four-day learning and networking experience. Don't miss your opportunity to network with experts in the field. To see the plenary and invited speakers and begin your travel plans, visit: www.tms.org/3DMS2020

CONGRESS ORGANIZERS

Lead Organizer: **Dorte Juul Jensen**, Technical University of Denmark, Denmark
Programming Chair: **Erica Lilleodden**, Helmholtz-Zentrum Geesthacht, Germany
Additional Organizers: **Scott Barnett**, Northwestern University, USA
Keith Knipling, Naval Research Laboratory, USA
Matthew P. Miller, Cornell University, USA
Akira Taniyama, Nippon Steel, Japan
Hiroyuki Toda, Kyushu University, Japan
Lei Zhang, Chinese Academy of Sciences, China

Sponsored by:

TMS
The Minerals, Metals & Materials Society

and the TMS Advanced Characterization,
Testing and Simulation Committee of the
Structural Materials Division

www.tms.org/3DMS2020